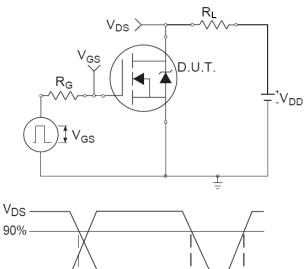
Features

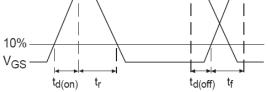
- $V_{DSS}=100V/V_{GSS}=\pm 20V/I_D=6.5A$ $R_{DS(ON)}=37m\Omega(max.)@V_{GS}=10V$
- Reliable and Rugged
- Advanced trench process technology
- High Density Cell Design For Low On-Resistance

Applications

- Power Management in Inverter System
- Boost for LED Backlight

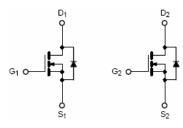
Switching Time Test Circuit and Waveforms



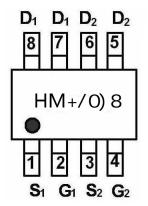


Package Marking and Ordering Information

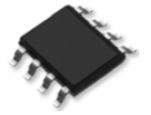
Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
ÁPTIÌJGOE	ÁPTIÌ JGOE		-	-	



Schematic diagram



Marking and pin Assignment



SOP-8 top view

Absolute Maximum Ratings (T_A=25°C unless otherwise noted)

Symbol	Parameter	Typical	Unit
V _{DSS}	Drain-Source Voltage	100	V
V _{GSS}	Gate –Source Voltage	±20	V
T	Continuous Drain Current T _C =100°C	6.5	Α
I _D	Continuous Drain Current	4.5	Α
I _{DP}	300us Pulsed Drain Current Tested $T_{C}=25^{\circ}C$	20	Α
Is	Diode Continuous Forward Current	6.5	Α
T_J	Operating Junction Temperature	150	°C
T _{STG}	Storage Temperature Range	-55 ~ 150	°C

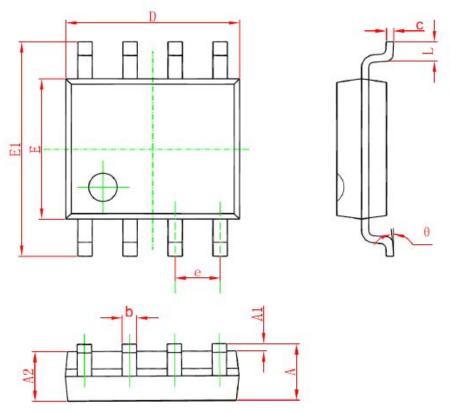
Electrical Characteristics (TA=25°C unless otherwise noted)

$\begin{tabular}{ c c c c c } \hline Static Characteristics & V_{GS} = 0V, I_D = 250uA & 100 & V \\ \hline BV_{DSS} & Drain-Source Breakdown Voltage V_{GS} = 0V, V_{GS} = 0V & 1 & uA \\ \hline I_{DSS} & Zero Gate Voltage Drain Current & V_{DS} = 80V, V_{GS} = 0V & 100 & V \\ \hline T_{J} = 125^\circ C & 100 & UA \\ \hline V_{GS(th)} & Gate Threshold Voltage & V_{DS} = V_{GS, I_D} = 250uA & 2 & 3.3 & 4 & V \\ \hline I_{GSS} & Gate Leakage Current & V_{GS} = \pm 20V, V_{DS} = 0V & \pm 100 & nA \\ \hline R_{DS(on)}^{-1} & Drain-Source On-Resistance & V_{GS} = 10V, I_D = 6.5A & 33 & 37 & m\Omega \\ \hline Diode Characteristics & & & & & & & & & & & & & & & & & & &$	Symbol	Parameter	Test Conditions	Min.	Тур	Max.	Unit		
$\begin{array}{c c c c c c c c c c c c c c c c c c c $	Static Characteristics								
$\begin{array}{ c c c c c c c c c c c c c c c c c c c$	BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V,I _D =250uA	100			V		
$\begin{tabular}{ c c c c c c c c c c c c c c c c c c c$	т	Zero Gate Voltage Drain Current	V_{DS} =80V, V_{GS} =0V			1	uA uA		
$\begin{array}{c c c c c c c c c c c c c c c c c c c $	I _{DSS}		T _J =125°C			100			
$\begin{array}{c c c c c c c c c c c c c c c c c c c $	V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} ,I _D =250uA	2	3.3	4	V		
$\begin{array}{c c c c c c c c c c c c c c c c c c c $		Gate Leakage Current	V_{GS} =±20V, V_{DS} =0V			±100	nA		
$\begin{array}{ c c c c c c } \hline \textbf{Diode Forward Voltage} & I_{SD}=6.5A, V_{GS}=0V & 1.1 & V \\ \hline t_{rr} & Reverse Recovery Time & I_{SD}=6.5A, & 60 & ns \\ \hline Q_{rr} & Reverse Recovery Charge & diF/dt=100A/us & 90 & nC \\ \hline \textbf{Dynamic Characteristics}^2 & & & & & & & & & & & & & & & & & & &$	1	Drain-Source On-Resistance	V _{GS} =10V, I _D =6.5A		33	37	mΩ		
$\begin{array}{c c c c c c c c c c c c c c c c c c c $									
$\begin{array}{c c c c c c c c c c c c c c c c c c c $	V_{SD}^{1}	Diode Forward Voltage	$I_{SD}=6.5A, V_{GS}=0V$			1.1	V		
$\begin{array}{c c c c c c c } \hline \textbf{Dynamic Characteristics}^2 \\ \hline \textbf{R}_G & \text{Gate Resistance} & V_{GS}=0V, V_{DS}=0V, \\ \hline \textbf{Frequency=1MHz} & 1.4 & \Omega \\ \hline \textbf{C}_{iss} & \text{Input Capacitance} & V_{GS}=0V, V_{DS}=30V \\ \hline \textbf{C}_{oss} & \text{Output Capacitance} & V_{GS}=0V, V_{DS}=30V \\ \hline \textbf{C}_{rss} & \text{Reverse Transfer Capacitance} & V_{GS}=0V, V_{DS}=30V \\ \hline \textbf{C}_{rss} & \text{Reverse Transfer Capacitance} & V_{GS}=0V, V_{DS}=30V \\ \hline \textbf{Turn-On Delay Time} & V_{DD}=50V, \textbf{R}_{L}=30\Omega \\ \hline \textbf{t}_r & \text{Turn-On Rise Time} & I_{D}=1.0A, V_{GEN}=10V \\ \hline \textbf{t}_f & \text{Turn-Off Delay Time} & R_G=6\Omega & 0 \\ \hline \textbf{t}_f & \text{Turn-Off Fall Time} & V_{DS}=50V, V_{GS}=10V \\ \hline \textbf{Gate Charge Characteristics}^2 & V_{DS}=50V, V_{GS}=10V \\ \hline \textbf{Q}_{gs} & \text{Gate-Source Charge} & V_{DS}=50V, V_{GS}=10V \\ \hline \textbf{L}_{D}=6.5A & 0 \\ \hline \textbf{L}_{D}=$	t _{rr}	Reverse Recovery Time	I _{SD} =6.5A,		60		ns		
$\begin{array}{ c c c c c c c }\hline R_G & Gate Resistance & V_{GS}=0V, V_{DS}=0V, \\ \hline Frequency=1MHz & 1.4 & \Omega \\ \hline C_{iss} & Input Capacitance & V_{GS}=0V, V_{DS}=30V \\ \hline C_{oss} & Output Capacitance & V_{GS}=0V, V_{DS}=30V \\ \hline C_{rss} & Reverse Transfer Capacitance & V_{Frequency=1MHz} & 2600 & PF \\ \hline \hline C_{rss} & Reverse Transfer Capacitance & V_{DD}=50V, R_L=30\Omega \\ \hline t_{d(on)} & Turn-On Delay Time & V_{DD}=50V, R_L=30\Omega \\ \hline t_r & Turn-On Rise Time & I_{D}=1.0A, V_{GEN}=10V \\ \hline t_f & Turn-Off Delay Time & R_G=6\Omega & 78 & 0 \\ \hline \hline Gate Charge Characteristics^2 & V_{DS}=50V, V_{GS}=10V \\ \hline Q_{gs} & Gate-Source Charge & V_{DS}=50V, V_{GS}=10V \\ \hline U_{D}=6.5A & 0 & 13.5 & nC \\ \hline \end{array}$	Qrr	Reverse Recovery Charge	diF/dt=100A/us		90		nC		
$\begin{array}{c c c c c c c c c c c c c c c c c c c $	Dynamic C	haracteristics ²							
$ \begin{array}{c c c c c c } \hline C_{iss} & Input Capacitance \\ \hline C_{oss} & Output Capacitance \\ \hline C_{rss} & Reverse Transfer Capacitance \\ \hline t_{d(on)} & Turn-On Delay Time \\ \hline t_{d(off)} & Turn-On Rise Time \\ \hline t_{d(off)} & Turn-Off Delay Time \\ \hline t_{f} & Turn-Off Fall Time \\ \hline t_{f} & Turn-Off Fall Time \\ \hline t_{g} & Total Gate Charge \\ \hline Q_{gs} & Gate-Source Charge \\ \hline Q_{gs} & Gate-Source Charge \\ \hline \end{array} \begin{array}{c} Frequency=1MHz \\ \hline V_{GS}=0V, V_{DS}=30V \\ Frequency=1MHz \\ \hline V_{DD}=50V, R_{L}=30\Omega \\ I_{D}=1.0A, V_{GEN}=10V \\ R_{G}=6\Omega \\ \hline \end{array} \begin{array}{c} 25 \\ 18 \\ I_{D}=1.0A, V_{GEN}=10V \\ \hline \end{array} \begin{array}{c} 18 \\ 60 \\ \hline \end{array} \begin{array}{c} 18 \\ 0 \\ 78 \\ \hline \end{array} \begin{array}{c} 18 \\ 78 \\ \hline \end{array} \begin{array}{c} 18 \\ 78 \\ \hline \end{array} \begin{array}{c} 18 \\ 18 \\ \hline \end{array} \begin{array}{c} 18 \\ 78 \\ \hline \end{array} \begin{array}{c} 18 \\ \hline \end{array} \begin{array}{c} 18 \\ 78 \\ \hline \end{array} \begin{array}{c} 113.5 \\ \hline \end{array} \begin{array}{c} 13.5 \\ \hline \end{array} \begin{array}{c} 10 \\ 13.5 \\ \hline \end{array} \begin{array}{c} 10 \\ 13.5 \\ \hline \end{array} \begin{array}{c} 10 \\ 10 \\ \hline \end{array} $	D .	Gate Resistance	$V_{GS}=0V, V_{DS}=0V,$		1.4		Ω		
$\begin{array}{c c c c c c c c c c c c c c c c c c c $			Frequency=1MHz		1.4				
$\begin{array}{c c c c c c c c c c c c c c c c c c c $	C _{iss}	Input Capacitance	$V_{} = 0 V V_{} = -20 V$		2000		pF		
$\begin{array}{c c c c c c c c c c c c c c c c c c c $		Output Capacitance	-		450				
$\begin{array}{c c c c c c c c c c c c c c c c c c c $	C _{rss}	Reverse Transfer Capacitance	riequency-nvinz		260				
$\begin{array}{c c c c c c c c c c c c c c c c c c c $		Turn-On Delay Time	V = 50 V D = 200		25				
$\begin{array}{c c c c c c c c c c c c c c c c c c c $	t _r	Turn-On Rise Time			18		ns		
t_f Turn-Off Fall Time R_G^{-0S2} 78Gate Charge Characteristics² Q_g Total Gate Charge $V_{DS}=50V, V_{GS}=10V$ 50 Q_{gs} Gate-Source Charge $I_D=6.5A$ 13.5nC	t _{d(off)}	Turn-Off Delay Time			60				
$\begin{array}{c c c c c c c c c c c c c c c c c c c $		Turn-Off Fall Time	NG-022		78				
$\begin{array}{c c c c c c c c c c c c c c c c c c c $	Gate Charg	ge Characteristics ²							
$\frac{Q_{gs}}{Q_{gs}} = \frac{Gate-Source Charge}{Gate-Source Charge} = \frac{V_{DS}=50V, V_{GS}=10V}{I_{D}=6.5A} = \frac{13.5}{12.5} = \frac{10V}{12.5}$			$\mathbf{M} = 50\mathbf{M}\mathbf{M} = 10\mathbf{M}$		50		nC		
	-17				13.5				
	Q _{gd}		$I_{\rm D}=0.3A$		11				

Note:

1: Pulse test ; pulse width \leq 300ns, duty cycle \leq 2%.

2: Guaranteed by design, not subject to production testing.



SOP-8 PACKAGE IN FORMATION

Symbol	Dimensions	n Millimeters	Dimensions In Inches			
	Min.	Max.	Min.	Max.		
A	2.200	2.400	0.087	0.094		
A1	0.000	0.127	0.000	0.005		
b	0.660	0.860	0.026	0.034		
с	0.460	0.580	0.018	0.023		
D	6.500	6.700	0.256	0.264		
D1	5.100	5.460	0.201	0.215		
D2	0.483	0.483 TYP.		0.190 TYP.		
E	6.000	6.200	0.236	0.244		
е	2.186	2.386	0.086	0.094		
L	9.800	10.400	0.386	0.409		
L1	2.900	2.900 TYP.		0.114 TYP.		
L2	1.400	1.700	0.055	0.067		
L3	1.600 TYP.		0.063 TYP.			
L4	0.600	1.000	0.024	0.039		
Φ	1.100	1.300	0.043	0.051		
θ	0°	8°	0°	8°		
h	0.000	0.300	0.000	0.012		
V	5.350 TYP.		0.211 TYP.			

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